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CO-003	Magazine Family DIP 7.62 mm Row Spacing	B	May 1978
CO-004	Square Magazine for DIP	B	May 1978
CO-005	Magazine for DIP 7.62, 10.16, 15.24 mm	A	May 1979
CO-006	Magazine for 68-Pin Chip Carrier	A	November 1982
CO-007	Pin Grid Array Pkg., .100" Centers	A	October 1987
CO-008	Fine Pitch Plastic Shipping Tube Family	A	July 1988
CO-009	Tab Tape Carrier 35, 48, 70 mm	A	July 1989
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CO-023	Plug Family Coinstack Magazine	A	July 1993
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CO-031	Thick Matrix Mini Tray	A	October 1995
CO-032	Thin Matrix Tray for Handling and Shipping Small Outline J Lead Packages	A	April 1996
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CO-034	Low Profile Matrix Tray for Handling and Shipping Thin Microelectronic Devices	D	February 2003
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DO-8	Axial Lead, Terminal Stud (see DO-205-AA)	B	June 1971
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DO-34	Axial Lead, Round Body (see DO-204-AG)	B	Archived – JEP 95
DO-35	Axial Lead, Round Body (see DO-204-AH)	B	Archived – JEP 95
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DO-37	Single-Ended Plastic with Shielded Prong	A	Archived – JEP 95
DO-38	Flat-Based Cylinder without Prong	A	Archived – JEP 95
DO-39	Axial Lead, Plastic	A	Archived – JEP 95
DO-40	Cylinder with Perpendicular Lead	A	Archived – JEP 95
DO-41	Axial Lead, Round Body (see DO-204-AL)	A	Archived – JEP 95
DO-42	Cylinder without Prongs	A	Archived – JEP 95
DO-43	Flange-Based Package with Terminal	A	Archived – JEP 95
DO-44	Flange-Based Package with Terminal	A	Archived – JEP 95
DO-45	Axial Lead, Single-Ended	A	Archived – JEP 95
DO-200	Disc Type	E	July 1985
DO-201	Axial Type, Round Body, Tapered-End	A	November 1972
DO-202	Axial Leads, Round	A	Archived – JEP 95
DO-203	Stud-hex Base, Solid Terminals	B	March 1973
DO-204 AA-AH	Lead Mounted Family (Round Lead Axial)	B	January 1976
DO-204 AJ-AM	Lead Mounted Family (Round Lead Axial)	C	July 1997
DO-204 AN-AR	Lead Mounted Family (Round Lead Axial)	B	July 1985
DO-205	Stud-Hex Base, Flex Terminals	C	February 1987
DO-206 AA-AB	Lead Mounted Family (Flat Lead Axial)	A	Archived – JEP 95
DO-207 AA	Leadless Device Family	A	Archived – JEP 95
DO-208	Single-End Press-Fit, Flanged	A	December 1972
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DO-215	Small Outline Plastic Surface Mount Gull Wing	C	June 1998
DO-216	S-PDSO-G2 Gullwing Plastic Surface-Mount	A	October 1995
DO-217	GADB-N Button Rectifier	A	May 1996
DO-218	Power Outline Plastic Surface Mount C-Bend	B	August 2000
DO-219	Outline Plastic Surface Mount Flat	B	February 2002
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MO-001 AJ-AM	Dual in-line Family 7.62 mm Row Spacing	F	June 1983
MO-001 AN-AP	Dual in-line Family 7.62 mm Row Spacing	B	October 1980
MO-002 AA-AH	Header Family .200" Pin Circle	B	October 1976
MO-002 AJ-AL	Header Family .200" Pin Circle	C	October 1976
MO-003 AA-AD	Replaced by MS-033 Variation AB	A	November 1999
MO-003 AE-AH	Replaced by MS-033 Variation AA	A	November 1999
MO-003 AJ	Replaced by MS-033 Variation AB	A	November 1999
MO-003 AK	Replaced by MS-033 Variation AA	A	November 1999
MO-004 AA	Replaced by MS-033 Variation AB	A	November 1999
MO-004 AB	Replaced by MS-033 Variation AB	A	November 1999
MO-004 AC	Replaced by MS-033 Variation AB	A	November 1999
MO-004 AD	Replaced by MS-033 Variation AA	A	November 1999
MO-004 AE	Replaced by MS-033 Variation AA	A	November 1999
MO-004 AF	Replaced by MS-033 Variation AB	A	November 1999
MO-004 AG	Replaced by MS-033 Variation AC	A	November 1999
MO-004 AH	Replaced by MS-033 Variation AC	A	November 1999
MO-004 AJ	Replaced by MS-033 Variation AB		
MO-004 AK	Replaced by MS-033 Variation AA	A	November 1999
MO-004 AL	Replaced by MS-033 Variation AC	A	November 1999
MO-004 AM	Flatpack Family .300" Width, .050" Pitch	C	November 1999
	RESCINDED		
MO-005	Grid Array Family, .125" Pitch	B	Archived – JEP 95
MO-006 AA-AD	Header Family 5.842 mm Pin Circle	C	October 1976
MO-006 AE-AH	Header Family 5.842 mm Pin Circle	D	October 1976
MO-007	Header Family, .141" Pin Circle	B	Archived – JEP 95
MO-008	Header Family, .100" Pin Circle	B	Archived – JEP 95
MO-009 AA-AB	Header Family, .200 Pin Circle	C	Archived – JEP 95
MO-010	Header Family, .065" Pitch	B	Archived – JEP 95
MO-011	Grid Array Family, 2.54 mm Pitch	B	Archived – JEP 95
MO-012 AA-AB	Quad Header Family, 2.54 mm Pitch	C	Archived – JEP 95
MO-013	Header Family, 11.89 mm Pin Circle	B	Archived – JEP 95
MO-014	Flange-Mounted Family Axial Lead	C	October 1976
MO-015 AA-AD	Dual In Line (DIP) Family 15.24 mm Row Spacing	D	June 1976
MO-015 AE-AH	Dual In Line (DIP) Family 15.24 mm Row Spacing	E	June 1977
MO-015 AJ-AM	Dual In Line (DIP) Family 15.24 mm Row Spacing	E	February 1981
MO-015	R-PDIP-T Dual Inline Plastic Family .600" Row Spacing	G	April 1993
MO-016	Dual In Line Plastic Family .900" Row Spacing	D	May 1990
MO-017	Axial Quad Family 2.54 mm Pitch	B	October 1976

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MO-019 AB	Replaced by MS-033 Variation AF	A	November 1999
MO-019 AC	Replaced by MS-033 Variation AE	A	November 1999
MO-019 AD	Replaced by MS-033 Variation AF	A	November 1999
MO-019 AE	Flatpack Family 10.16 mm Width, 1.27 Pitch RESCINDED	D	November 1999
MO-019 AF	Replaced by MS-033 Variation AF	A	November 1999
MO-020	Flatpack Family 12.70 mm Width, 1.27 Pitch	C	June 1976
MO-021	Flatpack Family 15.24 mm Width, 1.27 Pitch	C	June 1976
MO-022 AA-AD	Flatpack Family 17.780 mm Width, 1.27 Pitch	D	September 1977
MO-022 AE	Flatpack Family 17.780 mm Width, 1.27 Pitch	A	September 1977
MO-023	Flatpack Family 22.86 mm Width, 1.27 Pitch	C	June 1976
MO-024	Dual In Line (DIP) Family 12.70 mm Row Spacing	C	June 1976
MO-025	Flange Mounted Family Axial Lead 12.70 Pin Circle	B	October 1976
MO-026	Standard Dual-in-Line Family .400" Row Spacing (Plastic) .070" Lead Pitch	D	July 1991
MO-027	Leadless Flatpack Family 1.27 mm Terminal Space	A	February 1977
MO-028	Dual In Line (DIP) Family 5.08 mm Row Spacing	B	October 1976
MO-029	Quad In Line (QUIP) Family 5.08/10.16 mm Row Spacing	B	October 1976
MO-030	Quad In Line (QUIP) Family 19.05/23.50 mm Row Spacing	B	October 1976
MO-031	Quad In Line (QUIP) Family 5.08/10.16 mm Row Spacing	D	October 1979
MO-032 AA-AF	Flatpack Family 16.64 mm Width, 1.27 Pitch	C	February 1981
MO-033	Quad In Line (QUIP) Family 17.78/22.86 mm Row Spacing	B	February 1981
MO-034	Quad In Line (QUIP Family) .750/.925" Row Spacing	C	June 1990
MO-035	Single In Line (SIP) Family	A	September 1980
MO-036	Ceramic Dual-In-Line (DIP) Family .300" Row Spacing	B	November 1999
MO-037	Replaced by MS-031		
MO-038	Replaced by MS-032		
MO-039	Ceramic Side Ledged Dual In Line (DIP) Family 22.86 mm Row Spacing	A	April 1981
MO-040	Power Module	C	May 1983
MO-041 AA-AF	.050" Pitch Leadless Rectangular Chip Carrier Family (R-CQCC-N)	C	February 1995
MO-042	.050" Center Leadless Rectangular Chip Carrier	A	February 1983

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MO-044	Leaded Ceramic Chip Carrier .050" Center	A	September 1984
MO-045	Single In Line Power Module	A	September 1984
MO-046	Small Outline (SO) Package Peripheral Terminals 5.30 mm (.200") Wide Body	B	November 1984
MO-047	Plastic Chip Carrier (PCC) Family .050" Leadspace, Square	B	November 1988
MO-048	Plastic Flange-Mounted Header Family Multilead Registration	A	February 1987
MO-049	Not Published		
MO-050	Not Published		
MO-051	Not Published		
MO-052	Replaced by MS-016		
MO-053	Replaced by MO-069		September 1988
MO-054	Zig-Zag (ZIP) In Line Family 2.54mm Row Spacing	A	June 1986
MO-055	Ceramic Single In Line (SIP) Family	A	August 1986
MO-056	Ceramic .025" Center Chip Carrier	A	August 1986
MO-057	Ceramic .020" Center Chip Carrier	A	August 1986
MO-058 AA	Replaced by MS-030 AF		
MO-058 AB	Replaced by MS-030 AG		
MO-059	Small Outline (SO) Package Family 8.4 mm Body Width (Plastic)	B	January 1987
MO-060	.040" 132 Pin Quad Flatpack	B	November 1989
MO-061	Replaced by MS-027		June 1995
MO-062	Ceramic Chip Carrier 0.25" Center	A	April 1987
MO-063	Plastic Small Outline J-Lead (SOJ) .350" Body	A	April 1987
MO-064	30 Circuit Pluggable Single Inline Package (SIP) Tabs on .100" Centers	C	September 1992
MO-065	Plastic Small Outline J-Lead (SOJ) .300 Body Family	A	May 1987
MO-066	S-CPGA-P Pin Grid Array Family, .100" Pitch (Small Outline)	C	April 1994
MO-067	Pin Grid Array Family, .100" Pitch (Large Outline), S-CPGA-P	B	June 1993
MO-068	Edge Clip SIP Module Family .100 Row Centers	B	August 1991
MO-069	Plastic Quad Flat Pack .025" Lead Spacing (Gullwing)	B	October 1990
MO-070	.375" Width Flatpack NOT PUBLISHED	A	August 1987
MO-071	Plastic Thin Lead Package	B	July 1989
MO-072	Zig-Zag Inline Family (ZIP) 0.500" Max Seated Height	B	September 1990

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MO-074	Ceramic Bottom Brazed Dual In Line (DIP) Family .900 (22.86) Row Spacing	A	November 1987
MO-075	.50 Center Non-Hermetic Leadless Chip Carrier Quad Series	A	December 1987
MO-076	.050 Center Non-Hermetic Leadless Chip Carrier SO Series	A	December 1987
MO-077	Plastic Small Outline J-Lead Package Family (SOJ), .300" Wide Body, .050" Lead Pitch	D	November 1994
MO-078	Hermetic Flange-Mounted Header Family (Peripheral Terminals) Five Lead 2.54 Spacing	A	February 1988
MO-079	Flanged Family Peripheral lead .125 Pitch	A	March 1988
MO-080 AA-AB	ZIP Module Family 0.050" Pin Centers 0.100" Row Centers	A	September 1988
MO-081	Ceramic Quadpack Family .050" Pitch	A	March 1988
MO-082	Ceramic Quad Flat Pack .025" Lead Spacing (Gullwing)	A	May 1988
MO-083	.100" Center Plastic Pin Grid Array Family	A	December 1988
MO-084	Ceramic Quad Flat Pack 0.50" Lead Spacing (Gullwing)	A	July 1988
MO-085	.040" Center Rectangular Leadless Package (Staggered Terminals)	A	July 1988
MO-086	Low Profile Plastic Quad Flat Pack Family .025 Lead Spacing (Gullwing)	B	June 1990
MO-087	"J" Leaded Ceramic Cerquad Package Family - .050" Pitch	B	August 1991
MO-088 AA-AF	Small Outline J-Lead (SOJ) .300 Body Family (MS-113 body)	A	June 1988
MO-089	Plastic Quad Flat Pack .050" Lead Spacing (Gullwing)	A	November 1988
MO-090 AA-AF	Ceramic Quadpack Family .025" Lead Spacing	B	September 1989
MO-091	Plastic Small Outline J-Lead (SOJ) .350 Body Family	A	February 1989
MO-092	6.35 Mm Width Cerpak Registration	A	April 1989
MO-093	Flange-Mounted Header, 5-Lead	A	February 1990
MO-094	Molded Carrier Ring Family	C	March 1993
MO-095	Dual Incline (Wide Body) Plastic Family .300" Row Spacing	A	September 1989
MO-096	Flange-Mounted Header, 7-Lead	A	February 1990

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MO-097	Flange-Mounted Family Axial Lead .500" Pin Circle	A	July 1989
MO-098	Braze Lead Flatpack Registration	A	December 1989
MO-099	Small Outline (SO) Family Peripheral	A	October 1989
MO-100	Multilayer Ceramic Quad Flatpack .20 Spacing Gullwing (256 leads)	A	November 1989
MO-101	48 Pin Flatpack, Top Brazed	A	November 1989
MO-102	Tape Quad Flatpack RESCINDED	A	November 1992
MO-103	Replaced by MS-032	B	August 1999
MO-104	Ceramic Quad Flatpack, 0.25" Pitch, Gullwing Leadform	A	August 1991
MO-105	Thin Small Outline J-Lead (TSOJ) .300" Body, 0.050" Lead Pitch	A	August 1990
MO-106	Flatpack Family .535" Length, .030 Pitch	A	April 1990
MO-107	Ceramic Multilayer Leaded Chip Carrier .050" Pitch, J-Bend	A	May 1990
MO-108	Metric Plastic Quad Flat Pack Family, 1.0, 0.8, 0.65 Pitch PQFP-G/MQFP	C	August 1996
MO-109	Molded Carrier Ring Family	B	March 1993
MO-110	Round Lead, "J" form .050" Center Ceramic Chip Carrier	A	July 1990
MO-111	Round Lead, Gullwing .050" Center Ceramic Chip Carrier	A	July 1990
MO-112	Metric Plastic Quad Flatpack Family 3.9 mm Footprint	B	September 1995
MO-113	Ceramic Quadpack Family 0.25" Lead Spacing With Ceramic Nonconductive Tie Bar	D	August 1997
MO-114	Glass Sealed CQFP Family (GQFP-G)	C	January 1996
MO-115	32 Ld. Flatpack .480" Wide	A	November 1990
MO-116	Pluggable Single In-Line Memory Module (SIMM) With Tabs on .050 Centers	B	June 1998
MO-117	Small Outline Gullead 12 mm Body 0.80 mm Lead Spacing	A	June 1990
MO-118	Shrink Small Outline Package Family, 0.25" Lead Pitch .300" Wide Body Width (R-PDSO-G)	B	June 1993
MO-119	Plastic Small Outline (SO) Package Family With .300" Body Width	B	May 1992
MO-120	Plastic Small Outline (SO) Package Family With .350" Body Width	B	May 1992
MO-121	Plastic Small Outline (SO) Package Family With .330" Body Width	B	May 1992
MO-122	R-PDIP-T Thin Dual In Line Family .300" Row	A	August 1992

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MO-123	Spacing (Plastic) Small Outline J-Lead, 12 mm Body 0.80 mm Lead Spacing	A	June 1991
MO-124	Small Outline J-Lead Package Family (SOJ) 12.70 mm Body, 1.27 mm Lead Spacing	B	January 1994
MO-125	Ceramic Quad Flatpack .025" Pitch Gullwing Leadform	A	June 1991
MO-126	R-CDCC-N Leadless Small Outline Ceramic Chip Carrier .400" Body, .050" Pitch	B	June 1993
MO-127	Power Dual In-line	A	February 1992
MO-128 AA-BQ	.100" Center Staggered Pin Grid Array Family (Large Outline)	C	January 1997
MO-129	Top Brazed Ceramic Leaded Chip Carrier (.020" Lead Pitch) with Plastic Non-Conductive Tie Bar	A	September 1992
MO-130	Top Brazed Ceramic Leaded Chip Carrier (.015" Lead Pitch) with Plastic Non-Conductive Tie Bar	A	September 1992
MO-131	Top Brazed Ceramic Leaded Chip Carrier (.025" Lead Pitch) with Plastic Non-Conductive Tie Bar	A	September 1992
MO-132	Replaced by MS-025A		
MO-133	Replaced by MS-024		January 1995
MO-134	Ceramic Quad Flatpack Family (CQFP) 0.50 mm Lead Pitch with Ceramic Nonconductive Tie Bar	A	May 1992
MO-135	Thin Small Outline Package 12.70 mm Body Family (R-PDSO-G/TSOP II)	C	November 1993
MO-136	Replaced by MS-026		
MO-137	Plastic Shrink Small Outline Package (SSOP) Family 0.025" pitch 0.150" Body Width	E	March 2010
MO-138	16 Lead Flange Mounted Ceramic Power Package (Type 1), R-CDFM-T16	A	June 1993
MO-139	16 Lead Flange Mounted Ceramic Power Package (Type 2), R-CDFM-T16	A	June 1993
MO-140	18 Lead Flange Mounted Ceramic Power Package, R-CDFM-T16	A	June 1993
MO-141	Vertical Surface Mount Package 0.50 mm Lead Pitch, R-PSIP-X24	A	March 1993
MO-142	Thin Small Outline Package Type I, R-PDSO- G/TSOP II	D	July 2000
MO-143	Replaced by MS-029		June 1997
MO-144	Leadless Small Outline Ceramic Chip Carrier .350" Body, .050" Pitch, R-CDCC-N	A	June 1993
MO-145	S-CPGA-B/SMTPGA .050 Center Ceramic Surface	A	June 1993

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MO-146	Mount Pin Grid Array Family Registration Ceramic Flatpack Family .380" Width, .025 Pitch (R-GDFP-F)	A	July 1993
MO-147	Small Outline J-Lead Ceramic Chip Carrier .415" Body, .050" Lead Spacing (R-CDSO-J)	A	July 1993
MO-148	Multichip Module Ceramic Quad Flatpack (S-CQFP)	A	June 1993
MO-149	Tape Ball Grid Array Family	F	October 2003
MO-150	Plastic Shrink Small Outline Package (SSOP) - 5.3mm Body Width, 0.65mm Pitch, 1.25mm Lead Length (R-PDSO-G)	B	January 1994
MO-151	Replaced by MS-034		
MO-152	Plastic Shrink Small Outline Package (SSOP), R-PSDO-G/SSOP	C	January 1996
MO-153	Plastic Thin Shrink Small Outline Package (SSOP) R-PDSO-G/TSSOP/HTSSOP	F	May 2001
MO-154	Shrink Small Outline Package Family, 0.4 mm and .5 mm Lead Pitch, 3.9 mm Wide Body	C	April 1997
MO-155	5-Lead Small Outline Plastic (SOP) Package	A	November 1993
MO-156	Square Ceramic Ball Grid Array Family 1.00, 1.27, and 1.50 mm Pitch	C	April 2005
MO-157	Rectangular Ceramic Ball Grid Array Family 1.00, 1.27, and 1.50 mm Pitch	C	April 2005
MO-158	CBGA-X Ceramic Column Grid Array Family - Square	D	April 2002
MO-159	Ceramic Column Grid Array Family - Rectangular	B	June 1999
MO-160 AA-CC	72-Contact Dual Inline Memory Module (DIMM) Family, 1.27 Lead Centers	B	September 1995
MO-161	100 and 168 Pin Dual Inline Memory Module (DIMM) Family with Multiple Keyways, 1.27 mm Contact Centers	Ff	January 2003
MO-162	Plastic Flat Pack/Heat Slug Package 8 mm Pitch 48 Leads (S-PTFP-G48)	A	November 1993
MO-163	Replaced by MS-028		December 1997
MO-164	Plastic Small Outline Package, 9.90 mm Wide Body Family (R-PDSO-G)	A	January 1994
MO-165	Plastic Small Outline J-Lead, 10.15mm Body Family, .8mm Pitch	C	September 1996
MO-166 AA-AF	Plastic Small Outline Heat Slug Package, 20, 24, 30, 36 Leads	D	November 1999
MO-167	Pluggable Dual Inline Module, 1.27 mm Lead	C	October 1997

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	Centers 128-Pins		
MO-168 AA-AB	Plastic Isolated Flange-Mounted Header Family	A	January 1994
MO-169	Plastic Surface Mounted Header Family	B	November 2000
MO-170	68-Pin Card	A	February 1995
MO-171	88-Pin Card	A	February 1995
MO-172	Dual Inline Memory Module (DIMM) Family 112 & 300 Pin 1.27 mm Pitch	D	April 1999
MO-173	TFH-PQFP-G/TQHS Thin Quad Heat Spreader Family Registration	A	October 1995
MO-174	Plastic Small Outline Package, 70-pin .8 mm Pitch (R-PDSO-G/SOP)	A	January 1996
MO-175	Plastic Small Outline Package, 12.6 mm Body, 1.27 mm Lead Spacing	A	September 1995
MO-176	Ceramic Zig-Zag Inline Family (2.54 Row Spacing)	A	March 1995
MO-177	200 Pin Small Outline Dual Inline Memory Module (DIMM) Family, 0.65 mm Lead Centers	A	July 2001
	RESCINDED		
MO-178	Plastic Small Outline Package (SOT/SP), 5 Leads	C	February 2000
MO-179	Dual Inline Memory Module (DIMM) Family 1.00 Lead Centers (278-pin)	A	October 1995
MO-180	Plastic Small Outline Package (SOP) 13.3 mm Body Width	B	February 2001
MO-181	Metric Small Outline 16 mm Wide Body J-Lead Package (MSOJ)	A	January 1996
MO-182	Metric Thin Small Outline 16.00 mm Wide Body Package (MTSOP II)	C	September 1996
MO-183	Thin Small Outline Package Type I 0.55 mm Lead Pitch (TSOP I)	A	January 1996
MO-184	Plastic Small Outline Heat Slug Package	B	November 1999
MO-185	72 Pin Staggered Dual Inline Module (SDIM) Family, 1.27 Lead Centers	A	August 1996
MO-186	Solid State Floppy Disk Card (SSFDC)	C	March 1999
MO-187	Plastic Thin Shrink Small Outline Package 0.65 & 0.50 Pitch	F	September 2010
MO-188	Power PQFP Heat Slug Package (H-PQFP - G)	B	February 2000
MO-189	Plastic Quad Flat Heat Slug Package (2.0mm Thick 2.00 mm Footprint Quad & Dual-Sided Leads)	A	March 1996
MO-190	Small Outline Dual Inline Memory Module (DIMM) Family, 0.8 Lead Centers	D	January 2001
MO-191	Dual Inline Memory Module (DIMM) Family 1.27 Lead Centers, 160 Leads	A	December 1996

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MO-192	Low Profile Ball Grid Array Family	F	August 2003
MO-193	Plastic Thin Shrink Small Outline Package (Shrink SOT)	D	August 2010
MO-194	Plastic Thin Shrink Small Outline Package 0.40mm Lead Pitch	B	November 1997
MO-195	Thin Fine Pitch Ball Grid Array, 0.50mm Pitch	D	May 2006
MO-196	Plastic Ultra-Thin Small Outline No-Lead Package	C	June 1998
MO-197	Plastic Ultra-Thin Small Outline No-Lead Package	B	November 1997
MO-198	PQFP-B 3-Tier Family	A	April 1997
MO-199	Low Profile Small Outline J-Lead Package (LSOJ)	B	June 1999
MO-200	Small Outline J-Lead Package Assembly 2 High/4 High Stack	B	June 1999
MO-201	2 High/4 High Stacked TSOP II INACTIVATION NOTICE	A	June 2003
MO-202	Vertical Zig Zag Surface Mount Package 0.40mm Lead Pitch	A	March 1998
MO-203	Plastic Thin Shrink Outline Package (Shrink SOT)	C	August 2010
MO-204	Plastic Quad Flat Package Outline With Exposed Heat Sink	B	May 2001
MO-205	Low Profile, Fine Pitch, Ball Grid Array Family, 0.80mm Pitch, (Sq. & Rect.)	F	April 2003
MO-206	Dual Inline Memory Module (DIMM) Family 184 Pin DDR 1.27mm Contact Centers	E	January 2006
MO-207	Square & Rectangular Die-Size Ball Grid Array Family	M	December 2010
MO-208	Plastic Thin Fine Pitch Quad Flat No Lead Package	C	November 2001
MO-209	Plastic Thin Shrink Small Outline No Lead Package	A	November 1998
MO-210	Thin Fine Pitch Ball Grid Array Family (Rectangular/Square)	J	August 2007
MO-211	Die Size Ball Grid Array	C	June 2004
MO-212	Rectangular Plastic Quad Flat Package Outline 1.0mm Thick Body 3.20 Footprint	A	November 1998
MO-213	Horizontal Staggered Surface Mount Package 0.40mm Lead Pitch	A	November 1998
MO-214	Micro Dual Inline Memory Module Family, 0.5mm Lead Centers	B	September 2002
MO-215	SDRAM Dual Inline Memory Module (DIMM) Family, 1.00 mm Contact Centers INACTIVATION NOTICE	A	November 2000
MO-216	Thin Profile, Square and Rectangular, Ball Grid Array Family, 1.00 & 0.80 mm Pitches	E	August 2003

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MO-217	Very Very Thin Quad Bottom Terminal Chip Carrier Family	B	November 2001
MO-218	Plastic Flange-Mounted, Staggered Header Family	A	October 1999
MO-219	Low Profile, Fine Pitch, Ball Grid Array Family, 0.80 mm Pitch. (SQ.& RECT.)	G	January 2007
MO-220	Thermally Enhanced Plastic Very Thin and Very Very Thin Fine Pitch Quad Flat No Lead Package	K	June 2006
MO-221	Extremely Thin Profile Two Row Cavity Down 0.50 mm Pitch Ball Grid Array Family	C	May 2001
MO-222	Very Thin Profile, Fine Pitch, Land Grid Array Family, 0.50/0.65 mm PITCH, SQ/RECT	B.01	December 2010
MO-223	Plastic Thin Shrink Small Outline Package (Shrink SOT)	A	April 2000
MO-224	200 Pin DDR S.O. DIMM 0.60 mm Lead Centers	E	November 2006
MO-225	Very Thin Profile, Fine Pitch, Ball Grid Array Family 0.50/0.65 mm Pitch, SQ/RECT	C	August 2007
MO-226	Plastic Small Outline Heatslug Package 7.5mm Body Wide, 1.0mm Lead Pitch	B	February 2001
MO-227	DDR SRAM DIMM 1.00 mm Contact Centers	A	May 2003
	INACTIVATION NOTICE		
MO-228	Thin, Fine-Pitch Ball Grid Array Family, Dual Pitch	A	March 2001
MO-229	Thermally Enhanced Plastic Very Thin and Very Very Thin Fine Pitch Dual Flat No Lead Package	E	January 2010
MO-230	Plastic Small Outline with Exposed Heat Sink	A	March 2001
MO-231	Plastic Surface Mounted Header Family 21.50mm Body Width, 1.40mm LEAD PITCH	A	August 2001
MO-232	Low Profile Plastic Dual Flat No Lead Package	A	August 2001
MO-233	Rectangular Die-Size, Fine Dual Pitch Ball Grid Array Family	C	February 2003
MO-234	Low Profile Rectangular Ball Grid Array Family	B	September 2005
MO-235	Header Family Surface Mounted (Peripheral Terminals)	B	February 2003
MO-236	Plastic Ultra and Super Thin Small Outline, Non-Leaded Package	C	March 2010
MO-237	DDR2 SDRAM DIMM (Dual Inline Memory Module) Family 1.00mm Contact Centers	G.01	April 2011
MO-238	Stacked TSOP II Package Family (2 High)	A	February 2003
MO-239	Thermally Enhanced Plastic Very Thin Dual Row Fine Pitch Quad Flat No Lead Package	A	November 2002
MO-240	Thermally Enhanced 8 Lead 1.27 & 0.65MM Pitch,	B	October 2009

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MO-241	Low Profile Plastic Dual Flat No Lead Package	B	August 2003
MO-242	Dual Compatible Thermally Enhanced Plastic Very Thin Fine Pitch Quad Flat No Lead Package	C	September 2008
MO-243	Rectangular Die-Size, Stacked Ball Grid Array Family .80mm Pitch	A	August 2003
MO-244	Thermally Enhanced Plastic Very Thin and Very Thin Fine Pitch Bumped Quad Flat No lead	C	February 2008
MO-245	244 Pin DDR2 Mini DIMM 0.60 Lead Centers	A	September 2003
MO-246	High Profile Plastic Thermally Enhanced Enlarged Pitch Dual Flat No Lead Package	F	March 2009
MO-247	Rectangular Fine Pitch Thin Ball Grid Array 0.65 mm Pitch	D	May 2007
MO-248	Plastic Quad No-Lead Staggered Multi-Row Packages	E	June 2006
MO-249	Thermally Enhanced Plastic Ultra Thin and Extremely Thin Fine Pitch Quad Flat No Lead Package	A	January 2004
MO-250	Thin SO Package 8.89mm Body Family	A	November 2003
MO-251	Thermally Enhanced Plastic Very Thin and Very Thin Fine Pitch Bumped Quad Flat No Lead Package	A	February 2004
MO-252	Thermally Enhanced Plastic Very Thick Quad Flat No Lead Package	D	March 2010
MO-253	Plastic Very Very Thin Ultra Thin and Extremely Thin Fine Pitch Dual Small Outline Non-Leaded Package	B	February 2008
MO-254	14 & 16 Lead Screw Mount and Surface Mount Power Package	A	February 2004
MO-255	Thermally Enhanced Plastic Low and Thin Profile Fine Pitch Quad Flat No Lead Package	B	October 2005
MO-256	Plastic Very Very Thin Ultra Thin and Extremely Thin Fine Pitch Quad Flat Small Outline Non-Leaded Package	F	June 2007
MO-257	FB DIMM Family 1.00mm Contact Centers	B	May 2005
MO-258	Plastic Fine Pitch Quad No-Lead Staggered Two Row Thermally Enhanced Package Family	A	December 2004
MO-259	200 PIN DDR Mini DIMM 0.60 Lead Centers	A	March 2005
MO-260	Very Very Thin Small Outline Package Family	C	January 2007
MO-261	DDR and DDR2 Micro DIMM Mezzanine 214 Pin 0.4mm Lead Centers	A	June 2005
	Thick & Very Thick Fine Pitch Rectangular Ball		

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OUTLINE NUMBER	TITLE	ISSUE LETTER	DATE
MO-262	Grid Array Family 0.80mm Pitch Thermal Enhanced (Top Side) Plastic Very Thin and Very Very Thin Fine Pitch Quad Flat No Lead Package	A	September 2005
MO-263	Plastic Very Thin and Very Very Thin Fine Pitch Quad Flat No Lead Package	A	September 2005
MO-265	Thermally Enhanced Plastic Very Thin Fine Pitch Quad Flat No Lead Package Including Corner Terminals	A	November 2005
MO-266	Very Thin, Fine-Pitch, Stackable Ball Grid 0.50 mm Ball Pitch Array Family	C	January 2009
MO-267	Thermally Enhanced Plastic Very Thin Fine Pitch Quad Flat No Lead Package	B	March 2006
MO-268	204 Pin DDR3 S.O. DIMM 0.60 Lead Centers	C	August 2008
MO-269	DDR3 SDRAM DIMM 1.00mm Contact Centers	G	December 2009
MO-270	Extra Thin Profile, Fine Pitch, Internal Stacking Module (ISM) With Single Interconnect Array 0.75/0.80 mm Pitch SQ/RECT	B	June 2008
MO-271	Exposed Pad Plastic Small Outline Family 7.60 mm Body Width	A	May 2006
MO-272	Low Profile Exposed Pad Plastic Small Outline Family 3.90mm Body Width	A	May 2006
MO-273	Upper POP Package, Square, Fine Pitch, Ball Grid Array (0.65 and 0.50 mm Pitch)	C	March 2011
MO-274	DDR1/DDR2 16b/32b Small Outline Dual Inline Memory Module (SO-DIMM) Family 0.8 Lead Centers	A	July 2006
MO-275	Low Profile, Fine Pitch Ball Grid Array Family (SQ)	A	May 2006
MO-276	Low Profile, Rectangular Fine Pitch BGA 0.50mm Pitch LFR-XBGA	E	April 2011
MO-277	13 Pin Full Size MultimediaCard (MMC) Outline- MMCplus 32 X 24 X 1.4mm	A	September 2006
MO-278	13 Pin Reduced Size MultimediaCard (MMC) Outline-MMCmobile 18 X 24 X 1.4mm	A	September 2006
MO-279	10 Pin Micro Size MultimediaCard (MMC) Outline- MMCmicro 14 X 12 X 1.1mm	A	September 2006
MO-280	Ultra Thin and Very, Very Thin Profile, Fine Pitch Ball Grid Array Family (SQ.)	A	September 2006
MO-281	DDR2 SDRAM DIMM (Dual Inline Memory Module) Family, Flex-Based, 1.00mm Contact	A	November 2006

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	Centers		
MO-282	FB DIMM Family, Flex Based, 1.00 mm Contact Centers	A	January 2007
MO-283	Plastic Super-Thin And Die-Thin Profiles RFID Dipole Straps	B	January 2008
MO-284	Thin, Fine-Pitch, Rectangular Dual Pitch Ball Grid Array Family 0.80mm x 1.00mm Pitch	A	May 2007
MO-285	Very Thin Fine-Pitch Ball Grid Array Family Rectangular 0.50/0.65/0.80 mm Pitch	A	August 2007
MO-286	Plastic Small Outline, Wide Body SOIC, 7.5 Body Width, 0.65 Pitch	A	July 2007
MO-287	Small Scale, Plastic, Ultra, Extra and Super Thin, Fine Pitch, Dual Small Outline, No Lead Package	A	September 2007
MO-288	Small Scale Plastic Ultra Extra and Super Thin Fine Pitch Quad Flat No Lead Package (With Optional Thermal Enhancements)	B	September 2009
MO-290	DDR3 SDRAM DIMM Family Flex-Based, 1.00mm Contact Centers	A	November 2007
MO-291	Very Thin Fine Pitch Plastic Quad Flat Package 2.00mm Footprint	B	December 2008
MO-292	Very Thin Fine Pitch Plastic Quad Flat Package, 2.00mm Footprint	C	April 2010
MO-293	Plastic, Ultra, Extra and Super Thin Fine Pitch Dual Small Outline, Flat, Leaded Package	A	December 2008
MO-294	Very Thin Profile, Fine Pitch, SQ Bump Grid Array Family	A	December 2008
MO-295	Thin Profile Interstitial Fine Pitch Ball Grid Array Family (SQ)	A	January 2009
MO-296	Scalable Quad Flat No-Lead Packages, Square and Rectangular	A	February 2009
MO-297	SLIM LITE SSD Assembly	A	May 2009
MO-298	Thin, Very-Thin, Very Very Thin Profile Fine Pitch Ball Grid Array Family 0.40 mm Pitch	A	June 2009
MO-299	Surface Mount Power Package	A	November 2009
MO-300	mSATA SSD Assembly	B	October 2010
MO-301	Standard & Low, Fine Pitch Rectangular BGA Family 0.65mm Pitch	A	May 2010
MO-302	Very Thin Fine-Pitch Fully Overmolded Stackable Ball Grid Array Family 0.4mm Ball Pitch	A	April 2010
MO-304	100/170 Ball Grid Array Family Rectangular 1.0mm	A	February 2010

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	Pitch		
MO-306	Flange Mounted Family Surface Mount (Peripheral Terminals)	A	February 2011
SO-001	240 Pin DDRII SDRAM, 1.00mm Contact Centers	B	July 2003
SO-002	244 Pin MINIDIMM 0.60mm Lead Centers	B	February 2008
SO-003	FB DIMM 240 Position Socket Outline 1.00mm Contact Centers	B	August 2006
SO-004	Connector Outline for DDR and DDDR2 Micro DIMM Mezzanine 214 Pin 0.4mm Lead Centers	A	May 2005
SO-005	200 Pin Mini DIMM 0.60 mm Lead Centers	A	September 2005
SO-006	204 Pin SO-DDR3 SDRAM, 0.60mm Contact Centers, Socket Outline	B	October 2007
SO-007	DDR3 DIMM 240 Position Socket Outline 1.00mm Contact Centers	B	September 2008
SO-008	144 Pin, DDR1/DDR2 16b/32b Small Outline Dual Inline Memory Module (SO-DIMM) Family, 0.8 Lead Centers, Dual Notch, Socket Outline	A	October 2006
SO-009	DDR2 DIMM 240 Pin SMT Socket Outline 1.00mm Contact Centers	A	March 2007
SO-011	240 Pin DDR2 DIMM 1.00 mm Contact Centers Press Fit Socket Outline	A	September 2007
SO-012	240 Pin DDR3 DIMM 1.00 mm Contact Centers Press Fit Socket Outline	A	September 2007
SO-013	240 Pin FBDIMM 1.00 mm Contact Centers Press Fit Socket Outline	A	September 2007
SO-014	DDR3 DIMM 240 Pin SMT Socket Outline 1.0 mm Contact Centers	A	July 2008
TO-1	Metal Can		Archived – JEP 95
TO-2	Metal Can		Archived – JEP 95
TO-3	Diamond Base, .430 Pin Spacing	A	Archived – JEP 95
TO-4	MISSING		
TO-5	Axial Leads, .200 Pin Circle	A	Archived - JEP 95
TO-6	Press Fit		Archived – JEP 95
TO-7	Metal Can		Archived – JEP 95
TO-8	Axial Leads, .281 Pin Circle	A	Archived – JEP 95
TO-9	Axial Leads, .200 Pin Circle	A	Archived – JEP 95
TO-10	Stud-Mount, Solid Terminals		Archived – JEP 95
TO-11	Metal Can with Flange		Archived – JEP 95

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TO-12	Axial Leads, .200 Pin Circle	A	Archived – JEP 95
TO-13	Metal Can with Rigid Terminals		Archived – JEP 95
TO-14	Stud-Mount, Rigid Terminals		Archived – JEP 95
TO-15	Stud-Mount, Rigid Terminals		Archived – JEP 95
TO-16	Metal Can with Flange		Archived – JEP 95
TO-17	4 Axial Leads .071 Pin Circle		Archived – JEP 95
TO-18	Axial Leads, .100 Pin Circle	A	Archived – JEP 95
TO-19	MISSING		
TO-20	MISSING		
TO-21	MISSING		
TO-22	Flat Metal Can with Flange		Archived – JEP 95
TO-23	Cylindrical Metal Can with Flange		Archived – JEP 95
TO-24	Cylindrical Metal Can with Flange		Archived – JEP 95
TO-25	Cylindrical Metal Can with Flange		Archived – JEP 95
TO-26	Stud-Mounted Metal Can with Flange		Archived – JEP 95
TO-27	Diamond Flange with Holes and Rigid Leads		Archived – JEP 95
TO-28	Metal Can with Flange		Archived – JEP 95
TO-29	Metal Can with Flange		Archived – JEP 95
TO-30	Metal Can with Flange		Archived – JEP 95
TO-31	Metal Can with Stud Mount		Archived – JEP 95
TO-32	Metal Can with Stud Mount		Archived – JEP 95
TO-33	4 Axial Leads, .200 Pin Circle	A	Archived – JEP 95
TO-34	MISSING		
TO-35	MISSING		
TO-36	Stud-Mount .345 Pin Circle		Archived – JEP 95
TO-37	Diamond Base, .200 Pin Circle	A	Archived – JEP 95
TO-38	Cylindrical Metal Can with Flexible Leads		Archived – JEP 95
TO-39	Axial Leads, .200 Pin Circle	A	Archived – JEP 95
TO-40	Cylindrical Metal Can with Flange and Flexible Leads		Archived – JEP 95
TO-41	Diamond Base, .430 Pin Circle	A	Archived – JEP 95
TO-42	Axial Leads, .200 Pin Circle	A	Archived – JEP 95
TO-43	Cylindrical Metal Can with Flange and Flexible Leads		Archived – JEP 95
TO-44	Cylindrical Metal Can with Flange and Flexible Leads		Archived – JEP 95
TO-45	Cylindrical Metal Can with Flange and Flexible Leads		Archived – JEP 95
TO-46	Axial Leads, .100 Pin Circle	A	Archived – JEP 95
TO-47	Cylindrical Metal Can with Flange and Flexible Leads		Archived – JEP 95

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TO-48	Stud-Mount, Solid Leads	B	Archived – JEP 95
TO-49	Stud-Mount, Braided Terminal	B	Archived – JEP 95
TO-50	Strip Line Package		Archived – JEP 95
TO-51	Strip Line Package		Archived – JEP 95
TO-52	Axial Leads, .100 Pin Circle		Archived – JEP 95
TO-53	Flange-Mount, Rigid Leads		Archived – JEP 95
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TO-65	Stud-Mount, Solid Terminals		Archived – JEP 95
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TO-67	Stud-Mount Metal Can with Rigid Leads		Archived – JEP 95
TO-68	Stud-Mount Metal Can with Rigid Leads		Archived – JEP 95
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TO-74	10 Axial Leads, .200 Pin Circle	A	Archived – JEP 95
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TO-77	8 Axial Leads, .200 Pin Circle	A	Archived – JEP 95
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TO-79	8 Axial Leads, .200 Pin Circle	A	Archived – JEP 95
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TO-91	Double-Ended 10-Lead Flatpack	A	Archived – JEP 95
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TO-93	Stud-Mount, Flex Leads	B	Archived – JEP 95
TO-94	Stud-Mount, Flex Leads	B	Archived – JEP 95
TO-95	Double-Ended 14-Lead Flatpack	A	Archived – JEP 95
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TO-97	10 Axial Leads, .230 Pin Circle	A	Archived – JEP 95
TO-98	In-Line Axial Leads, Indexed	C	Archived – JEP 95
TO-99	8 Axial Leads, .200 Pin Circle	A	Archived – JEP 95
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TO-105	Epoxy Cylinder with Axial Leads	A	Archived – JEP 95
TO-106	Epoxy Cylinder with Axial Leads	A	Archived – JEP 95
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TO-131	Strip Line Package, 4 Leads	A	Archived – JEP 95
TO-132	Stud-Mount with Flexible Leads	A	Archived – JEP 95
TO-200 AA-AD	Disc Type Family	I	April 1984
TO-200 AE-AF	Disc Type Family	J	July 1985
TO-201	Coaxial Family	B	Archived – JEP 95
TO-202	Tab-Mounted Peripheral Leads	F	February 1978
TO-203	Press-Fit Family - Solid Leads	C	Archived – JEP 95
TO-204 AA-AE	Flange-Mounted Header Family (.430) Pin Spacing	C	November 1982
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TO-206	Header Type .100 Pin Circle	B	November 1982
TO-207	Stud-Header Family, .690 Pin Circle	A	Archived – JEP 95
TO-208 AA-AD	Stud Hex Base Family (Solid Terminals)	A	June 1974
TO-208 AE-AG	Stud Hex Base Family (Solid Terminals)	C	May 1979
TO-209	Stud-Hex, Flexible Terminals	A	June 1974
TO-210 AA-AE	Stud-Hex Base Family (Solid Terminals)	A	Archived – JEP 95
TO-211 MA-MB	Stud-Hex Base Family (Solid Leads)	A	Archived – JEP 95
TO-212 MA	Stud-Hex Base Family (Solid Leads)	A	Archived – JEP 95
TO-213	Flange-Mounted Header, .200 Spacing	A	September 1976
TO-214	Stud-Hex Base Family (Solid Leads)	A	Archived – JEP 95
TO-215	Coaxial Type	A	June 1971
TO-216	Stud-Mounted Stripline	A	June 1971
TO-217	Stud Rectangular Base Family	A	Archived – JEP 95
TO-218	Flange-Mounted Header	E	June 1986
TO-219	Flange-Mounted Header	B	December 1977
TO-220	Flange-Mounted Header	K	April 2002
TO-221 AA-AB	Flat-Mounted Peripheral Leads	A	Archived – JEP 95
TO-222 AA-AB	Header Family (.200 Pin Circle)	A	Archived – JEP 95
TO-223 AA-AB	Header Family (.100 Pin Circle)	A	Archived – JEP 95
TO-224 AA	Disc Family - Peripheral Leads	A	Archived – JEP 95
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TO-226 AE	Header Family, Flat Index	A	December 1981
TO-227 AA-AC	Disc Family Peripheral Leads	A	Archived – JEP 95
TO-228 AA-AC	Stud-Mounted Family (Peripheral Terminals)	A	Archived – JEP 95
TO-229	Stripline Header Family	A	Archived – JEP 95
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TO-238	Flange-Mounted Header, Rectangular	D	March 1982
TO-239 AA-AB	Flange Mounted Header Family (Cylindrical Body) .490 Pin Circle	B	Archived – JEP 95
TO-240	Terminal Strip Power Module	B	March 1981
TO-241	Header Family(.100 Pin Circle)	A	Archived – JEP 95
TO-242	Header Family Flange Mounted (.100 Pin Circle)	A	Archived – JEP 95
TO-243	Header Family, Peripheral Terminal	C	July 1986
TO-244	Flange-Mounted Rectangular Base	B	September 1984
TO-245	Header Family, .100 Pin Circle DRAWING NOT AVAILABLE		
TO-246	Header Family, .200 Pin Circle DRAWING NOT AVAILABLE		
TO-247	Flange-Mounted Header Family	E	June 2004
TO-248	Power Module	A	Archived – JEP 95
TO-249	Flange Mounted Family (Rectangular Base)	B	Archived – JEP 95
TO-250	4-Lead DIP .300” Spacing	A	July 1985
TO-251	Header Family, Peripheral Terminals	D	June 2002
TO-252	Flange Mounted Family Surface Mount	E	June 2004
TO-253	Plastic Small Outline Package (SOT/SOP), 4 Leads	D	January 1999
TO-254	Flange-Mounted, Peripheral Leads	A	November 1986
TO-255	Disc Family, Peripheral Leads Not Published		December 1987
TO-256	Flat Mounted Transistor	A	March 1988
TO-257	Flange Mounted Header Family (Peripheral Terminals)	C	September 1996
TO-258	Flange-Mounted 5.08 Spacing	A	February 1988
TO-259	Flange-Mounted Header Family	B	April 1991
TO-260	Ceramic Header Axial 3-Lead	A	April 1989
TO-261	Plastic Small Outline Package SOP/SOT	C	May 2002
TO-262	Flange-Mounted Header Family	A	June 1990
TO-263	Plastic Surface Mounted Header Family	E	July 2007
TO-264	Header Family Insertion Mount (Peripheral Terminals)	B	November 1993
TO-265	3 Lead Flange Mounted Ceramic Power Package	A	June 1993
TO-266	Opto Family Insertion Mount (Peripheral Terminals)	A	April 1994
TO-267	Hermetic Flange Mounted Header Family (Peripheral Terminals) Three Lead, 5.0 Spacing	A	September 1994
TO-268	Header Family Surface Mounted (Peripheral Terminals)	A	June 1995
TO-269	Small Outline Surface Mount (R-PDSO-G4)	A	August 1996
TO-270	Two Lead Surface Mount Power Package	C	July 2008
TO-271	Quad Flat Pack Surface Mount Thermally Enhanced	A	May 1998

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TO-274	Plastic Clip Mounted Package, 3 Leads	A	March 2000
TO-275	Plastic Flange Mounted Power Package, 2 Leads	A	November 2000
TO-276	Ceramic No Lead Chip Carrier	A	January 2001
TO-277	Small Outlines Plastic Surface Mount Package	A	January 2006
TO-278	Thin Profile, 3 Lead Plastic Small Outline Surface Mount	B	November 2006
TO-279	Plastic Surface Mounted Header Family	B	August 2008
TO-280	Flange Mounted Header Family	A	August 2010
UO-001	14 Beam Chip	B	Archived – JEP 95
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UO-016	34 Beam Chip	A	Archived – JEP 95
UO-017	Tape Automated Bonding Uncased Outline	A	October 1988
UO-018	Tape Automated Bonding (TAB) Package Family	B	July 1993